VERSION SHOWING THE CHANGES TO THE CLAIMS

This listing replaces all prior listings.

IN THE CLAIMS

Amend the claims as follows:

1 (Currently amended). An electronic component comprising a plurality of predominantly organic functional layers at least one of which layers is a lower layer and at least one other of the layers is a central layer, ~~which~~ said layers being coupled to ~~has~~ at least one through-plating, ~~(3) whose~~ having a cross-sectional profile which extends through the layers transversely to the layers and which through plating extends at least in part below the at least one central functional layer, has non-sharp contours and/or is at least in part in the shape of a truncated cone, whereby prior to the application of the through plating to the at least one central functional layer ~~(Figures 1 through 8) is so characteristic that it can be seen therefrom that prior to the application of at least one central functional layer (4, 5)~~ the at least one lower functional layer ~~(2) was~~ is locally treated with the through plating.

2 (Currently amended). The ~~An~~ electronic component as set forth in claim 1 wherein the cross-sectional profile of the through plating comprises ~~shows as the through-plating (3)~~ a free-standing raised portion of electrically conductive or non-conductive material.

3 (Currently amended). The ~~An~~ electronic component as set forth in claim 2 wherein the conductive material includes polyaniline, pedot, carbon black, graphite,

conducting silver and/or metal and/or a mixture thereof.

4(Currently amended). The ~~An~~ electronic component as set forth in claim 2 including a non-conducting material wherein at least one of the central functional layer ~~(4, 5)~~ and~~/or~~ the non-conducting material includes an insulating material such as polyhydroxystyrene, polymethylmethacrylate and/or polystyrene and/or a semiconducting material such as polyalkylthiophene and/or polyfluorene and/or a mixture thereof.

5(Currently amended). The ~~An~~ electronic component as set forth in claim 1 ~~one of the preceding claims~~ wherein ~~the surface of~~ the through-plating ~~(3)~~ is in the form of a raised portion that has a surface ~~has a~~ roughness which promotes ~~later~~ contacting.

6(Currently amended). The ~~An~~ electronic component as set forth in one of the preceding claims wherein the cross-sectional profile shows a chemical treatment at least of a lower functional layer ~~(2)~~.

7(Currently amended). The ~~An~~ electronic component as set forth in one ~~of~~ ~~the preceding~~ claims 1-5 wherein the cross-sectional profile shows a physical treatment of at least ~~of~~ a lower functional layer ~~(2)~~.

8(Currently amended). The ~~An~~ electronic component as set forth in one of ~~the preceding~~ claims 1-5 wherein the cross-sectional profile shows a local disruption

location ~~(7)~~ on the at least one lower functional layer.

9(Currently amended). The ~~An~~ electronic component as set forth in one of ~~the preceding~~ claims 1-5 wherein the cross-sectional profile shows a preceding locally restricted change in the surface energy of the at least one lower functional layer ~~(2)~~, at which no wetting by a subsequently applied organic material of a subsequent central functional layer ~~(4, 5)~~ occurred.

10(Currently amended). The ~~An~~ electronic component as set forth in one of ~~the preceding~~ claims 1-5 wherein a disruption location is produced ~~material (7)~~ locally on the at least one ~~applied to the~~ lower functional layer ~~(2)~~ chemically by application of a material, at which prior to or after application of one of the central functional layers the dislocation can be detected by at least one of material residues, the shape of the disruption location and/or traces on the at least one lower functional layer ~~is removed again prior to or after application of the central functional layer (4,5)~~.

11(Currently amended). The ~~An~~ electronic component as set forth in one of ~~the preceding~~ claims 1-5 wherein the component is made up of a plastic substrate which includes one of the following materials: PET, PP, PEN, polyimide, polyamide and/or coated paper.

12(Currently amended). A process for the production of at least one through-plating of an electronic component comprising predominantly organic material and an

insulating layer, wherein the through-plating is formed prior to application of the insulating layer.

13(Currently amended). The use ~~Use~~ of the ~~a~~ component as set forth in one of claims 1 through 5 ~~11~~ in an ~~for the production of~~ electronic ~~lowest-cost~~ products ~~such as RFID tags, labels and/or others~~.